# IEEE Transactions on Industrial Cyber-Physical Systems

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- ICPS Technologies
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- Engineering and Management of Systems of ICPS

- Artificial Intelligence Empowered ICPS
- Trustworthy and Reliable ICPS
- Applications of ICPS
- Education and Training for ICPS

The transitioning toward an SOA-based ICPS architecture
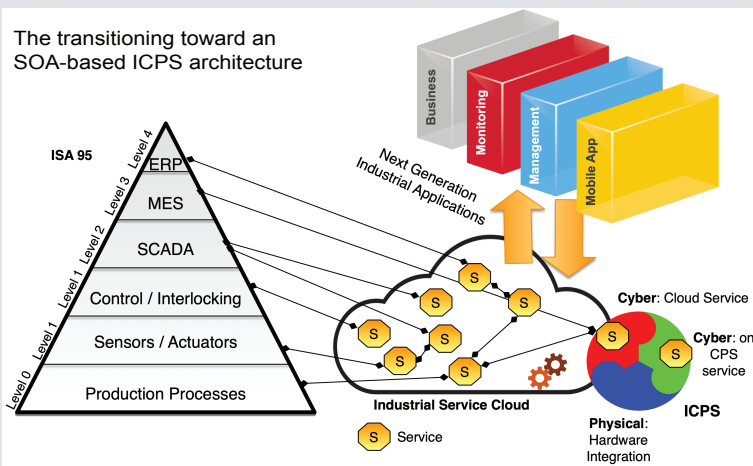
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